

ICS83023

Dual, 1-TO-1

DIFFERENTIAL-TO-LVCMOS FANOUT BUFFER

GENERAL DESCRIPTION

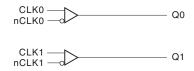


The ICS83023 is a dual, 1-to-1 Differential-to-LVCMOS Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS83023 has 2 differential clock input pairs.

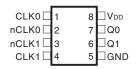
FEATURES

- 2 LVCMOS / LVTTL outputs
- 2 Differential CLKx, nCLKx input pairs
- CLK, nCLK pairs can accept the following differential input levels: LVDS, LVPECL, LVHSTL, SSTL, HCSL
- Output frequency: 350MHz (typical)
- Output skew: 60ps (typical)
- Part-to-part skew: 500ps (maximum)
- Small 8 lead SOIC package saves board space
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature
- Pin-to-pin compatible with MC100EPT23

BLOCK DIAGRAM



PIN ASSIGNMENT



ICS83023 8-Lead SOIC

3.8mm x 4.8mm, x 1.47mm package body **M Package** Top View



ICS83023

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TABLE 1. PIN DESCRIPTIONS

Number	Name	Туре		Description
1	CLK0	Input	Pulldown	Non-inverting differential clock input.
2	nCLK0	Input	Pullup	Inverting differential clock input.
3	nCLK1	Input	Pullup	Inverting differential clock input.
4	CLK1	Input	Pulldown	Non-inverting differential clock input.
5	GND	Power		Power supply ground. Connect to ground.
6	Q1	Output		Single clock output. LVCMOS / LVTTL interface levels.
7	Q0	Output		Single clock output. LVCMOS / LVTTL interface levels.
8	V _{DD}	Power		Positive supply pin. Connect to 3.3V.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance				4	pF
C _{PD}	Power Dissipation Capacitance (per output)	V _{DD} = 3.6V				pF
R _{PULLUP}	Input Pullup Resistor			51		ΚΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		ΚΩ
R _{OUT}	Output Impedance			7		Ω



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ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD} 4.6V

 $\begin{array}{ll} \text{Inputs, V}_{\text{I}} & -0.5\text{V to V}_{\text{DD}} + 0.5\text{V} \\ \text{Outputs, V}_{\text{O}} & -0.5\text{V to V}_{\text{DD}} + 0.5\text{V} \\ \text{Package Thermal Impedance, } \theta_{\text{JA}} & 112.7^{\circ}\text{C/W (0 Ifpm)} \\ \text{Storage Temperature, T}_{\text{STG}} & -65^{\circ}\text{C to } 150^{\circ}\text{C} \\ \end{array}$

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 3A. Power Supply DC Characteristics, $V_{DD} = 3.3V \pm 0.3V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{DD}	Positive Supply Voltage		3.0	3.3	3.6	V
I _{DD}	Positive Supply Current			11		mA

Table 3B. LVCMOS / LVTTL DC Characteristics, $V_{DD} = 3.3V \pm 0.3V$, TA = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{OH}	Output High Voltage; NOTE 1		2.6			V
V _{OL}	Output Low Voltage; NOTE 1				0.5	V

NOTE 1: Outputs terminated with 50Ω to $V_{DD}/2$. See Parameter Measurement Section, 3.3V Output Load Test Circuit.

Table 3C. Differential DC Characteristics, $V_{DD} = 3.3V \pm 0.3V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	nCLK0, nCLK1	$V_{IN} = V_{DD} = 3.6V$			5	μΑ
I _{IH}		CLK0, CLK1	$V_{IN} = V_{DD} = 3.6V$			150	μΑ
I	Input Low Current	nCLK0, nCLK1	$V_{IN} = 0V, V_{DD} = 3.6V$	-150			μΑ
		CLK0, CLK1	$V_{IN} = 0V, V_{DD} = 3.6V$	-5			μΑ
V _{PP}	Peak-to-Peak Input Voltage			0.15		1.3	V
V _{CMR}	Common Mode Input Voltage; NOTE 1, 2			GND + 0.5		V _{DD} - 0.85	V

NOTE 1: For single-ended applications, the maximum input voltage for CLKx, nCLKx is V_{DD} + 0.3V.

NOTE 2: Common mode voltage is defined as $\rm V_{\rm in}$



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Table 4. AC Characteristics, $V_{DD} = 3.3V \pm 0.3V$, $TA = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency			350		MHz
t _{PD}	Propagation Delay; NOTE 1			2.8		ns
tsk(o)	Output Skew; NOTE 2, 4			60		ps
tsk(pp)	Part-to-Part Skew; NOTE 3, 4				500	ps
t _R	Output Rise Time	0.8V to 2V		250		ps
t _F	Output Fall Time	0.8V to 2V		250		ps
odc	Output Duty Cycle			50		%

All parameters measured at f_{MAX} unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to $V_{\rm DD}/2$ of the output.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at $V_{DD}/2$.

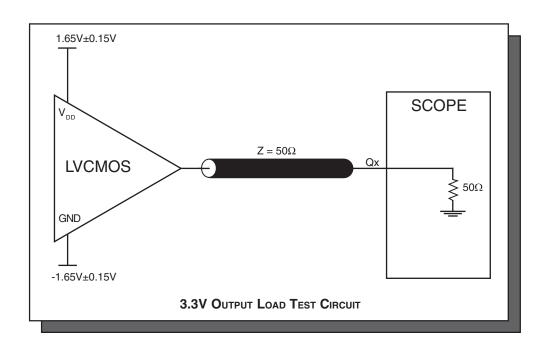
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DD}/2$.

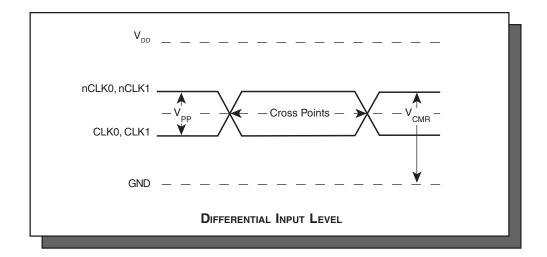
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

ICS83023

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PARAMETER MEASUREMENT INFORMATION

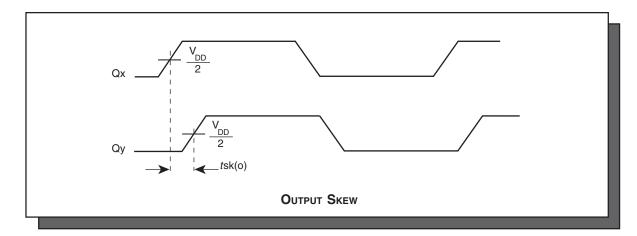


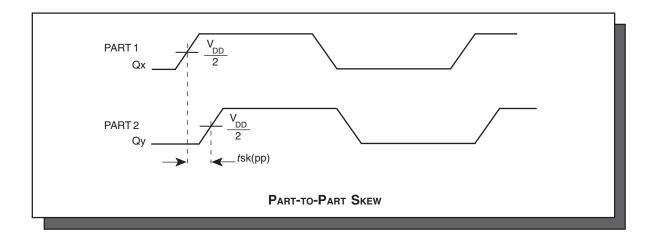


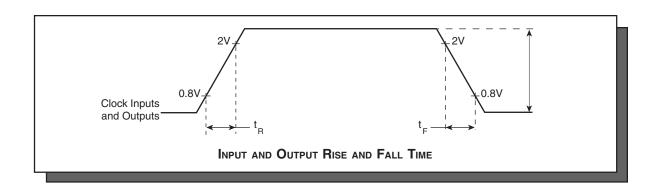


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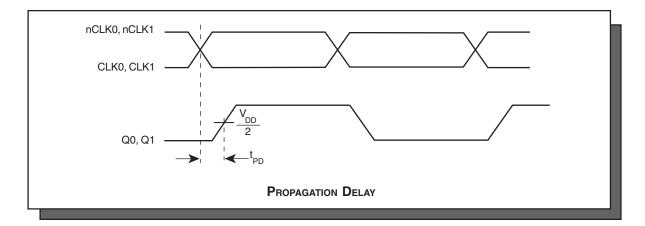


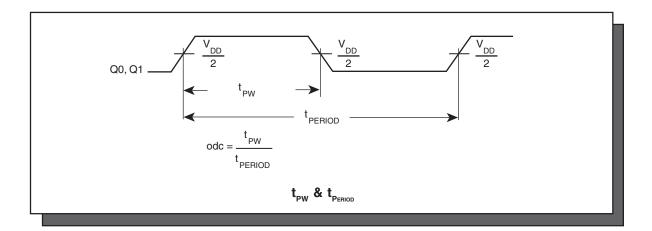




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Table 5. θ_{JA} vs. Air Flow Table

θ_{JA} by Velocity (Linear Feet per Minute)

0 200 500 Single-Layer PCB, JEDEC Standard Test Boards 153.3°C/W 128.5°C/W 115.5°C/W Multi-Layer PCB, JEDEC Standard Test Boards 97.1°C/W 112.7°C/W 103.3°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

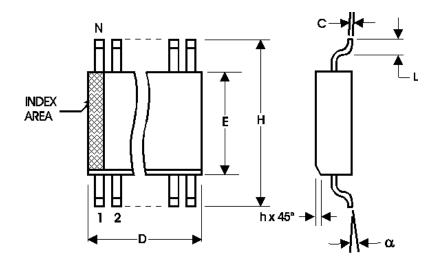
TRANSISTOR COUNT

The transistor count for ICS83023 is: 416

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PACKAGE OUTLINE - SUFFIX M



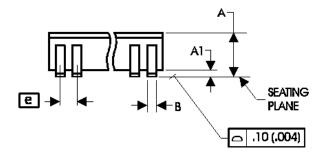


TABLE 6. PACKAGE DIMENSIONS

SYMBOL	Millin	neters	
STWBOL	MINIMUN	MAXIMUM	
N	8	3	
А	1.35	1.75	
A1	0.10	0.25	
В	0.33	0.51	
С	0.19	0.25	
D	4.80	5.00	
E	3.80	4.00	
е	1.27 BASIC		
Н	5.80	6.20	
h	0.25	0.50	
L	0.40	1.27	
α	0°	8°	

Reference Document: JEDEC Publication 95, MS-012



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TABLE 7. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS83023AM	83023AM	8 lead SOIC	96 per tube	-40°C to 85°C
ICS83023AM	83023AM	8 lead SOIC on Tape and Reel	2500	-40°C to 85°C

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